

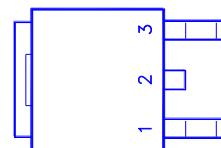
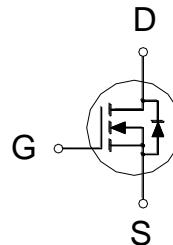
NIKO-SEM
**N-Channel Enhancement Mode
Field Effect Transistor**
P0920BD

TO-252

Halogen-Free & Lead-Free

**PRODUCT SUMMARY**

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
200V	0.42Ω	9A



1. GATE
2. DRAIN
3. SOURCE

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Gate-Source Voltage		V_{GS}	± 20	V
Continuous Drain Current	$T_C = 25^\circ\text{C}$	I_D	9	A
	$T_C = 100^\circ\text{C}$		5	
Pulsed Drain Current ¹		I_{DM}	31	
Avalanche Current		I_{AS}	9	
Avalanche Energy	$L = 2.8\text{mH}$	E_{AS}	113	mJ
Power Dissipation	$T_C = 25^\circ\text{C}$	P_D	62.5	W
	$T_C = 100^\circ\text{C}$		25	
Operating Junction & Storage Temperature Range		T_j, T_{stg}	-55 to 150	°C

THERMAL RESISTANCE RATING

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	$R_{\theta JC}$		2	°C / W

¹Pulse width limited by maximum junction temperature.**ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, Unless Otherwise Noted)**

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$	200			V
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	1	2	3	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 200\text{V}, V_{GS} = 0\text{V}$			1	μA
		$V_{DS} = 160\text{V}, V_{GS} = 0\text{V}, T_J = 125^\circ\text{C}$			10	
Drain-Source On-State Resistance ¹	$R_{DS(\text{ON})}$	$V_{GS} = 4.5\text{V}, I_D = 4.5\text{A}$		0.35	0.48	Ω
		$V_{GS} = 10\text{V}, I_D = 4.5\text{A}$		0.33	0.42	

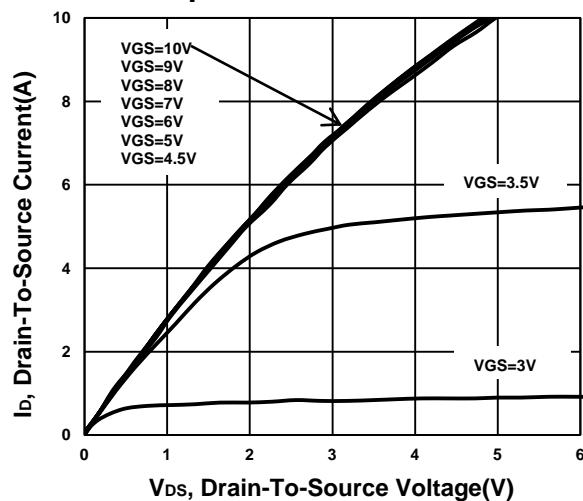
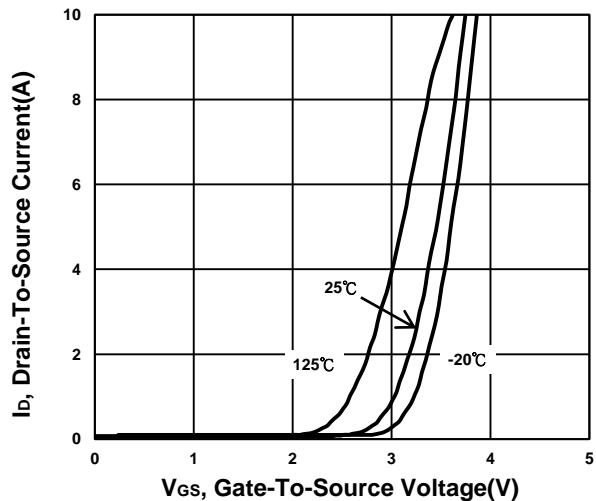
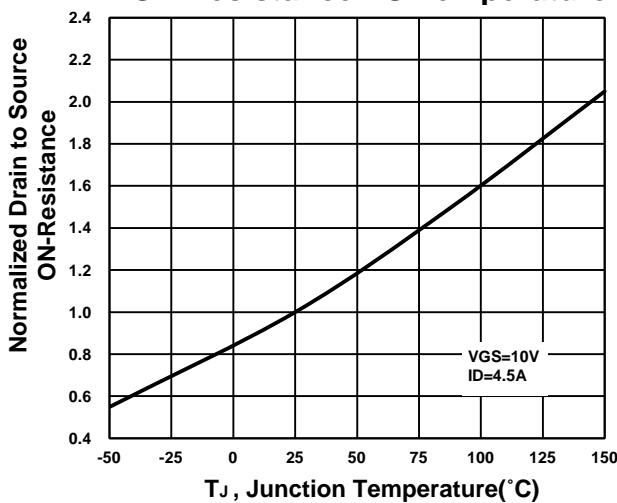
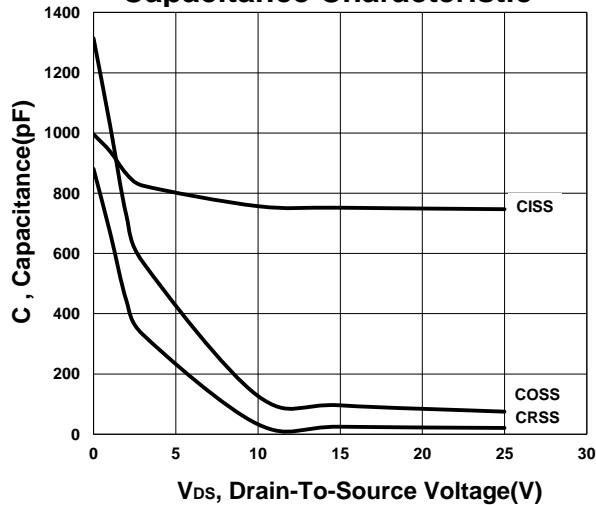
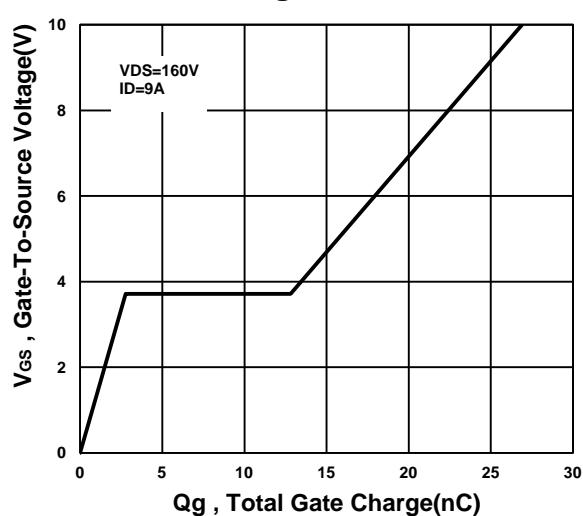
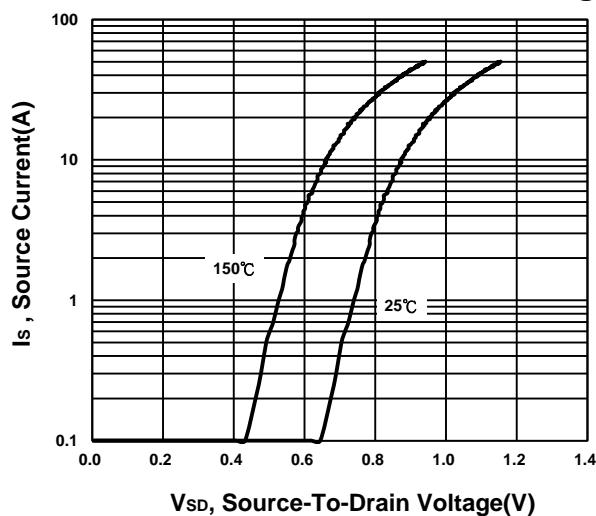
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Forward Transconductance ¹	g_{fs}	$V_{DS} = 10V, I_D = 4.5A$		10		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = 25V, f = 1MHz$		759		nF
Output Capacitance	C_{oss}			77		
Reverse Transfer Capacitance	C_{rss}			21		
Total Gate Charge ²	Q_g	$V_{DS} = 160V, V_{GS} = 10V, I_D = 9A$		29.5		nC
Gate-Source Charge ²	Q_{gs}			2.8		
Gate-Drain Charge ²	Q_{gd}			11		
Turn-On Delay Time ²	$t_{d(on)}$	$V_{DD} = 100V, I_D \cong 9A, V_{GS} = 10V, R_{GEN} = 6\Omega$		28		nS
Rise Time ²	t_r			99		
Turn-Off Delay Time ²	$t_{d(off)}$			85		
Fall Time ²	t_f			97		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_J = 25^\circ C$)						
Continuous Current ²	I_S			9	A	
Forward Voltage ¹	V_{SD}	$I_F = 9A, V_{GS} = 0V$		1.6	V	
Reverse Recovery Time	t_{rr}	$I_F = 9A, dI_F/dt = 100A / \mu S$		159		nS
Reverse Recovery Charge	Q_{rr}			822		nC

¹Pulse test : Pulse Width $\leq 300 \mu sec$, Duty Cycle $\leq 2\%$.²Independent of operating temperature.

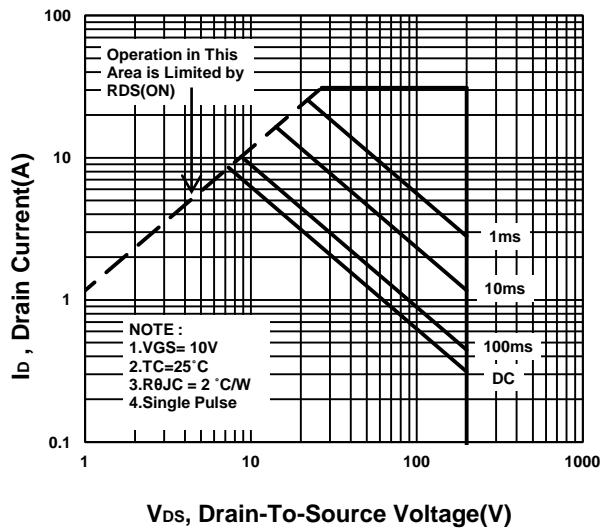
NIKO-SEM**N-Channel Enhancement Mode
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Halogen-Free & Lead-Free****Output Characteristics****Transfer Characteristics****On-Resistance VS Temperature****Capacitance Characteristic****Gate charge Characteristics****Source-Drain Diode Forward Voltage**

NIKO-SEM

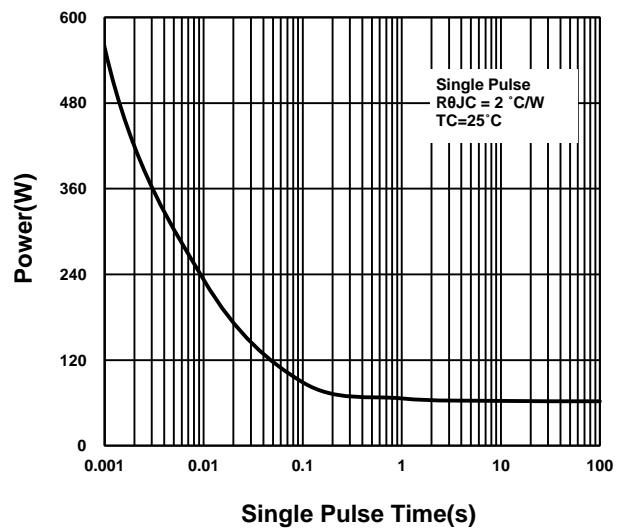
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Safe Operating Area



Single Pulse Maximum Power Dissipation



Transient Thermal Response Curve

